

CMOS 14-Stage Ripple-Carry Binary Counter/Divider and Oscillator

High-Voltage Types (20-Volt Rating)

■ CD4060B consists of an oscillator section and 14 ripple-carry binary counter stages. The oscillator configuration allows design of either RC or crystal oscillator circuits. A RESET input is provided which resets the counter to the all-0's state and disables the oscillator. A high level on the RESET line accomplishes the reset function. All counter stages are master-slave flip-flops. The state of the counter is advanced one step in binary order on the negative transition of ϕ_1 (and ϕ_0). All inputs and outputs are fully buffered. Schmitt trigger action on the input-pulse line permits unlimited input-pulse rise and fall times.

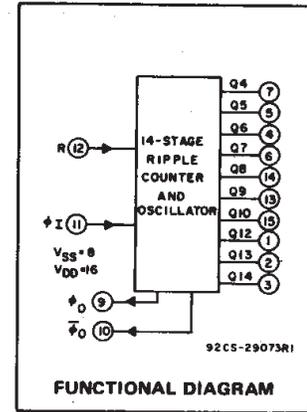
The CD4060B-series types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

Features:

- 12 MHz clock rate at 15 V
- Common reset
- Fully static operation
- Buffered inputs and outputs
- Schmitt trigger input-pulse line
- 100% tested for quiescent current at 20 V
- Standardized, symmetrical output characteristics
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for description of "B" Series CMOS Devices"

Oscillator Features:

- All active components on chip
- RC or crystal oscillator configuration
- RC oscillator frequency of 690 kHz min. at 15 V



Applications

- Control counters
- Timers
- Frequency dividers
- Time-delay circuits

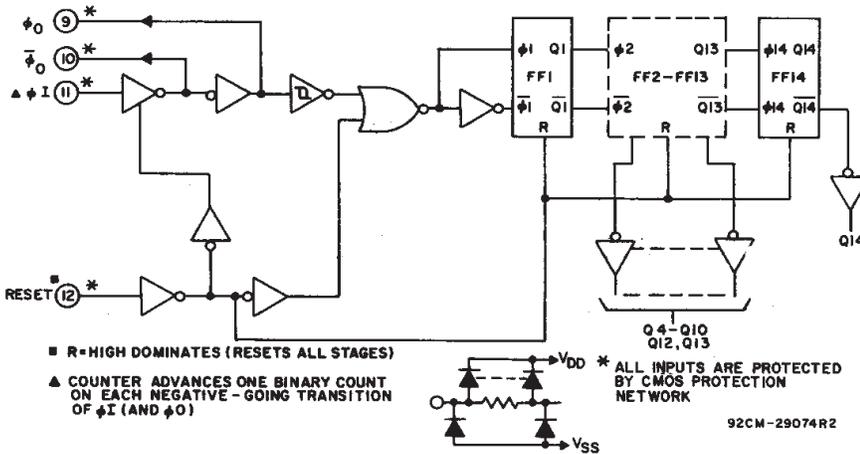


Fig. 1 – Logic diagram.

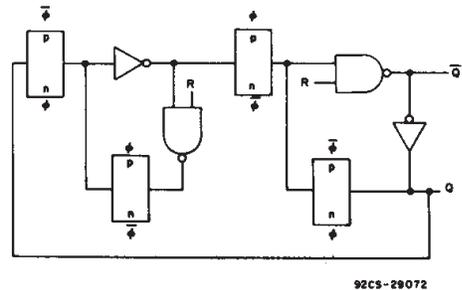


Fig. 2 – Detail of typical flip-flop stage.

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V_{DD})	-0.5V to +20V
Voltages referenced to V_{SS} Terminal	
INPUT VOLTAGE RANGE, ALL INPUTS	-0.5V to $V_{DD} + 0.5V$
DC INPUT CURRENT, ANY ONE INPUT	$\pm 10\text{mA}$
POWER DISSIPATION PER PACKAGE (P_D):		
For $T_A = -55^\circ\text{C}$ to $+100^\circ\text{C}$	500mW
For $T_A = +100^\circ\text{C}$ to $+125^\circ\text{C}$	Derate Linearly at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR		
FOR $T_A = \text{FULL PACKAGE-TEMPERATURE RANGE (All Package Types)}$	100mW
OPERATING-TEMPERATURE RANGE (T_A)	-55°C to $+125^\circ\text{C}$
STORAGE TEMPERATURE RANGE (T_{stg})	-65°C to $+150^\circ\text{C}$
LEAD TEMPERATURE (DURING SOLDERING):		
At distance $1/16 \pm 1/32$ inch ($1.59 \pm 0.79\text{mm}$) from case for 10s max	$+265^\circ\text{C}$

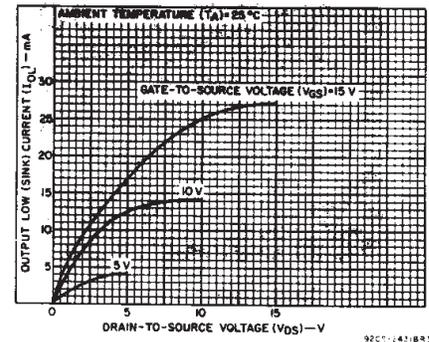


Fig. 3 – Typical n-channel output low (sink) current characteristics.

CD4060B Types

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V _O (V)	V _{IN} (V)	V _{DD} (V)	-55	-40	+85	+125	+25			
								Min.	Typ.	Max.	
Quiescent Device Current, I _{DD} Max.	—	0,5	5	5	5	150	150	—	0,04	5	μA
	—	0,10	10	10	10	300	300	—	0,04	10	
	—	0,15	15	20	20	600	600	—	0,04	20	
	—	0,20	20	100	100	3000	3000	—	0,08	100	
Output Low (Sink) Current*, I _{OL} Min.	0,4	0,5	5	0,64	0,61	0,42	0,36	0,51	1	—	mA
	0,5	0,10	10	1,6	1,5	1,1	0,9	1,3	2,6	—	
	1,5	0,15	15	4,2	4	2,8	2,4	3,4	6,8	—	
Output High (Source) Current*, I _{OH} Min.	4,6	0,5	5	-0,64	-0,61	-0,42	-0,36	-0,51	-1	—	mA
	2,5	0,5	5	-2	-1,8	-1,3	-1,15	-1,6	-3,2	—	
	9,5	0,10	10	-1,6	-1,5	-1,1	-0,9	-1,3	-2,6	—	
	13,5	0,15	15	-4,2	-4	-2,8	-2,4	-3,4	-6,8	—	
Output Voltage: Low-Level, V _{OL} Max.	—	0,5	5	0,05				—	0	0,05	V
	—	0,10	10	0,05				—	0	0,05	
	—	0,15	15	0,05				—	0	0,05	
Output Voltage: High-Level, V _{OH} Min.	—	0,5	5	4,95				4,95	5	—	V
	—	0,10	10	9,95				9,95	10	—	
	—	0,15	15	14,95				14,95	15	—	
Input Low Voltage V _{IL} Max.	0,5, 4,5	—	5	1,5				—	—	1,5	V
	1,9	—	10	3				—	—	3	
	1,5, 13,5	—	15	4				—	—	4	
Input High Voltage, V _{IH} Min.	0,5, 4,5	—	5	3,5				3,5	—	—	V
	1,9	—	10	7				7	—	—	
	1,5, 13,5	—	15	11				11	—	—	
Input Current I _{IN} Max.	—	0,18	18	±0,1	±0,1	±1	±1	—	±10 ⁻⁵	±0,1	μA

*Data not applicable to terminal 9 or 10.

RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges

CHARACTERISTIC	V _{DD}	LIMITS		UNITS
		MIN.	MAX.	
Supply-Voltage Range (For T _A = Full Package Temperature Range)	—	3	18	V
Input-Pulse Width, t _W (f = 100 kHz)	5	100	—	ns
	10	40	—	
	15	30	—	
Input-Pulse Rise Time and Fall Time, t _{rφ} , t _{fφ}	5	Unlimited		
	10	Unlimited		
	15	Unlimited		
Input-Pulse Frequency, f _{φI} (External pulse source)	5	—	3,5	MHz
	10	—	8	
	15	—	12	
Reset Pulse Width, t _W	5	120	—	ns
	10	60	—	
	15	40	—	

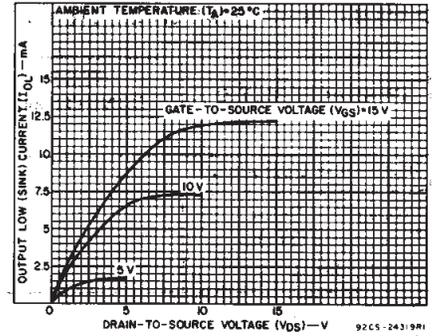


Fig. 4 - Minimum n-channel output low (sink) current characteristics.

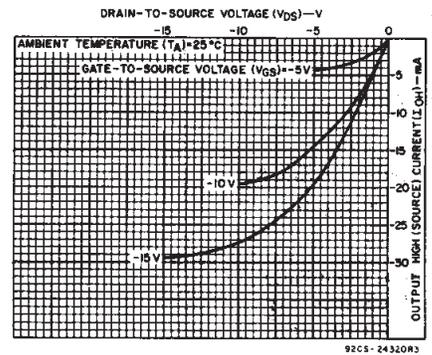


Fig. 5 - Typical p-channel output high (source) current characteristics.

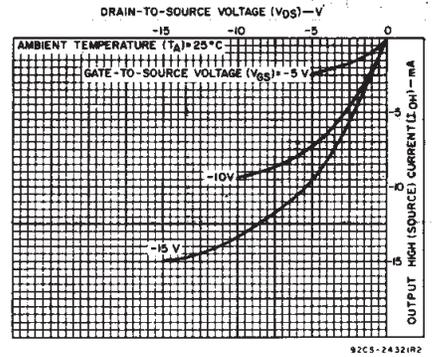


Fig. 6 - Minimum p-channel output high (source) current characteristics.

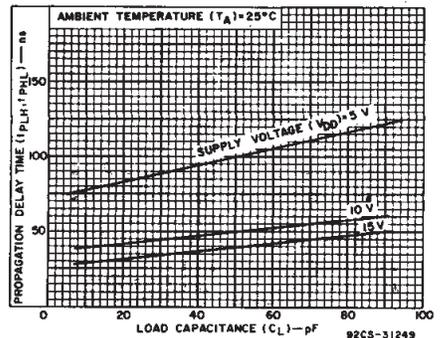


Fig. 7 - Typical propagation delay time (Q_n to Q_{n+1}) as a function of load capacitance.

3
COMMERCIAL CMOS
HIGH VOLTAGE ICs

CD4060B Types

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 25^\circ\text{C}$, Input $t_r, t_f = 20\text{ ns}$,
 $C_L = 50\text{ pF}$, $R_L = 200\text{ k}\Omega$

CHARACTERISTIC	TEST CONDITIONS	LIMITS			UNITS	
		V _{DD} (V)	MIN.	TYP.		MAX.
Input-Pulse Operation						
Propagation Delay Time, ϕ_I to Q4 Out; t_{PHL}, t_{PLH}		5	—	370	740	ns
		10	—	150	300	
		15	—	100	200	
Propagation Delay Time, Q_n to Q_{n+1} ; t_{PHL}, t_{PLH}		5	—	100	200	ns
		10	—	50	100	
		15	—	40	80	
Transition Time, t_{THL}, t_{TLH}		5	—	100	200	ns
		10	—	50	100	
		15	—	40	80	
Min. Input-Pulse Width, t_W	$f = 100\text{ kHz}$	5	—	50	100	ns
		10	—	20	40	
		15	—	15	30	
Input-Pulse Rise & Fall Time, $t_{r\phi}, t_{f\phi}$		5	Unlimited			ns
		10				
		15				
Max. Input-Pulse Frequency, $f_{\phi I}$ (External pulse source)		5	3.5	7	—	MHz
		10	8	16	—	
		15	12	24	—	
Input Capacitance, C_I	Any Input		—	5	7.5	pF
Reset Operation						
Propagation Delay Time, t_{PHL}		5	—	180	360	ns
		10	—	80	160	
		15	—	50	100	
Minimum Reset Pulse Width, t_W		5	—	60	120	ns
		10	—	30	60	
		15	—	20	40	

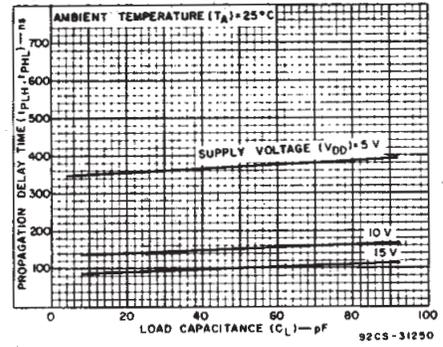


Fig. 8 - Typical propagation delay time (ϕ_I to Q₄ Output) as a function of load capacitance.

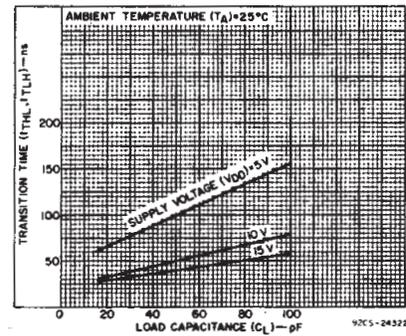


Fig. 9 - Typical transition time as a function of load capacitance.

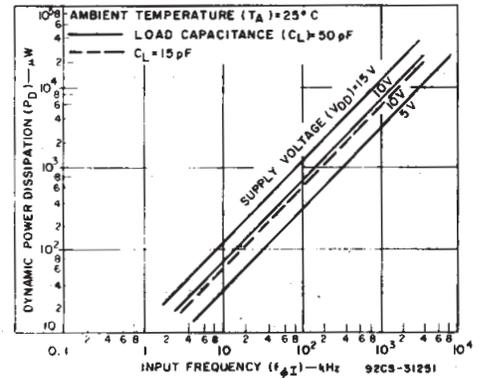


Fig. 10 - Typical dynamic power dissipation as a function of input frequency.

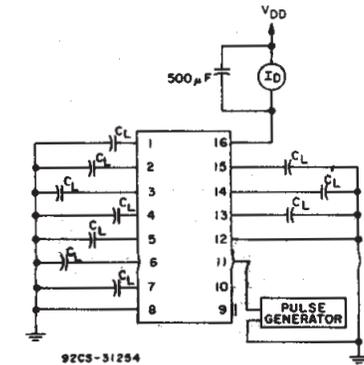


Fig. 11 - Dynamic power dissipation test circuit.

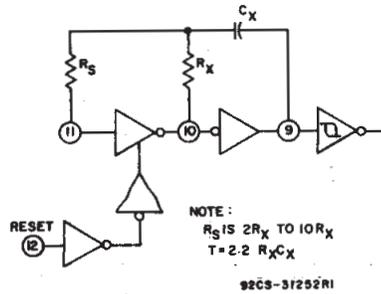


Fig. 12 - Typical RC circuit.

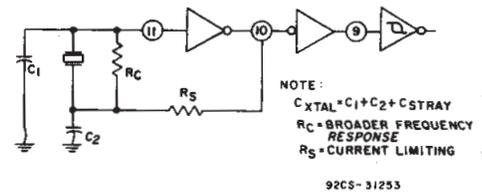


Fig. 13 - Typical crystal circuit.

CD4060B Types

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 25^\circ\text{C}$, Input $t_r, t_f = 20 \text{ ns}$, $C_L = 50 \text{ pF}$, $R_L = 200 \text{ k}\Omega$ [cont'd]

CHARACTERISTIC	TEST CONDITIONS	VDD (V)	LIMITS			UNITS	
			Min.	Typ.	Max.		
RC Operation							
Variation of Frequency (Unit-to-Unit)	$C_X = 200 \text{ pF}$, $R_S = 560 \text{ k}\Omega$, $R_X = 50 \text{ k}\Omega$	5	—	$23 \pm 10\%$	—	kHz	
		10	—	$24 \pm 10\%$	—		
		15	—	$25 \pm 10\%$	—		
Variation of Frequency with voltage change (Same Unit)	$C_X = 200 \text{ pF}$, $R_S = 560 \text{ k}\Omega$, $R_X = 50 \text{ k}\Omega$	5V to 10 V 10V to 15V	—	1.5 0.5	—	M Ω	
R_X max.	$C_X = 10 \text{ }\mu\text{F}$ $= 50 \text{ }\mu\text{F}$ $= 10 \text{ }\mu\text{F}$	5	—	—	20		
		10	—	—	20		
		15	—	—	10		
C_X max.	$R_X = 500 \text{ k}\Omega$ $= 300 \text{ k}\Omega$ $= 300 \text{ k}\Omega$	5	—	—	1000	μF	
		10	—	—	50		
		15	—	—	50		
Maximum Oscillator Frequency*	$R_X = 5 \text{ k}\Omega$ $R_S = 30 \text{ k}\Omega$ $C_X = 15 \text{ pF}$	10	530	650	810	kHz	
		15	690	800	940		
Drive Current at Pin 9 (For Oscillator Design)	I_{OL}	$V_O = 0.4 \text{ V}$	5	0.16	0.35	—	mA
		$= 0.5 \text{ V}$	10	0.42	0.8	—	
		$= 1.5 \text{ V}$	15	1	2	—	
	I_{OH}	$V_O = 4.6 \text{ V}$	5	-0.16	-0.35	—	
		$= 9.5 \text{ V}$	10	-0.42	-0.8	—	
		$= 13.5 \text{ V}$	15	-1	-2	—	

*RC oscillator applications are not recommended at supply voltages below 7 V for $R_X < 50 \text{ k}\Omega$.

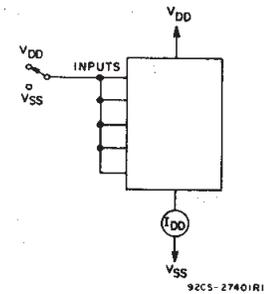


Fig. 14 – Quiescent device current.

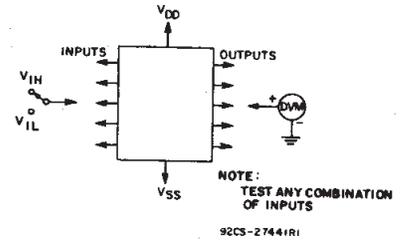


Fig. 15 – Input voltage.

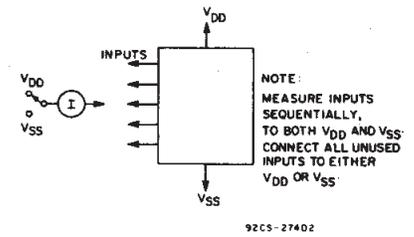
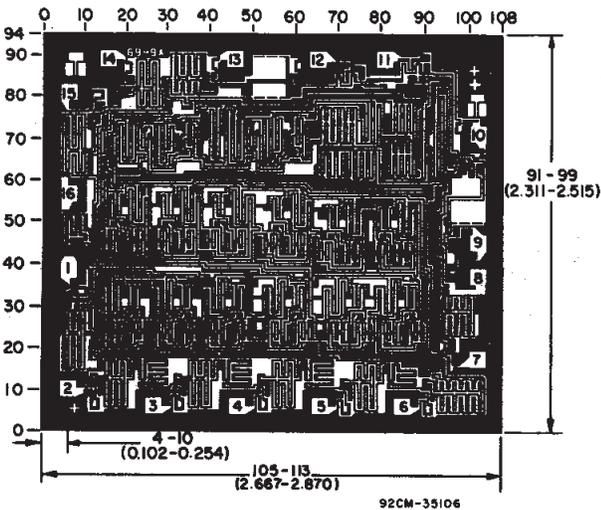


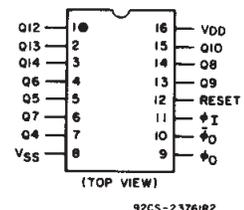
Fig. 16 – Input current.

3
COMMERCIAL CMOS
HIGH VOLTAGE ICs



Chip dimensions and pad layout for CD4060B

TERMINAL DIAGRAM



Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DSP	dsp.ti.com
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
Low Power Wireless	www.ti.com/lpw

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2007, Texas Instruments Incorporated

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD4060BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4060BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4060BF	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD4060BF3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD4060BF3AS2534	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
CD4060BM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4060BM96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4060BM96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4060BM96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4060BME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4060BMG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4060BMT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4060BMTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4060BMTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4060BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4060BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4060BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4060BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4060BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4060BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4060BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4060BPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4060BPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

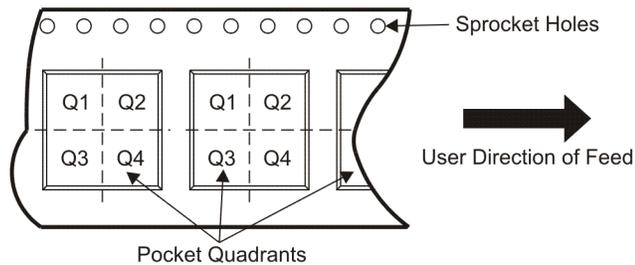
Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



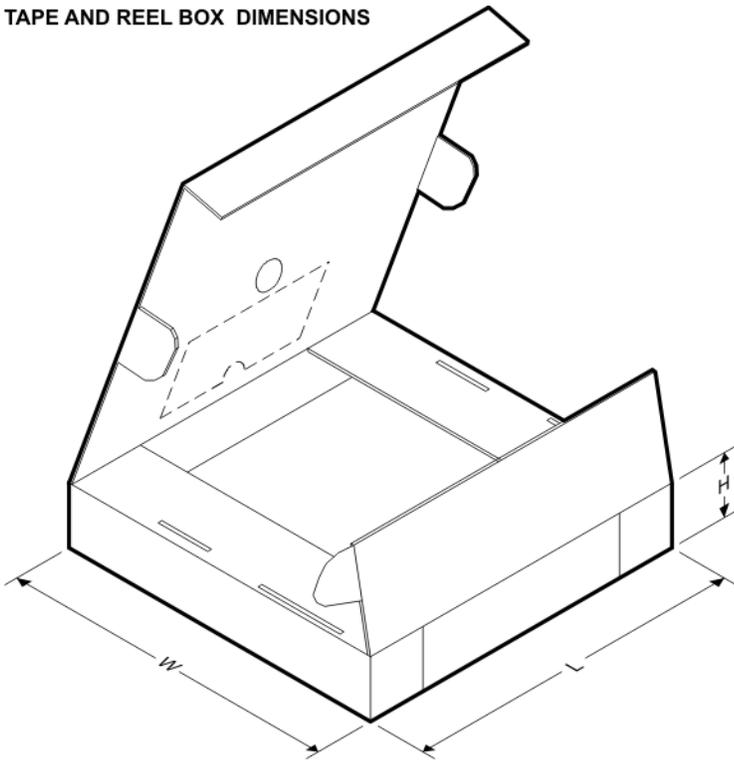
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4060BM96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD4060BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4060BPWR	TSSOP	PW	16	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4060BM96	SOIC	D	16	2500	333.2	345.9	28.6
CD4060BNSR	SO	NS	16	2000	346.0	346.0	33.0
CD4060BPWR	TSSOP	PW	16	2000	346.0	346.0	29.0

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN

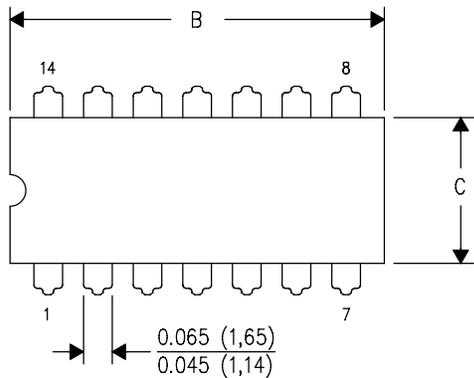


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

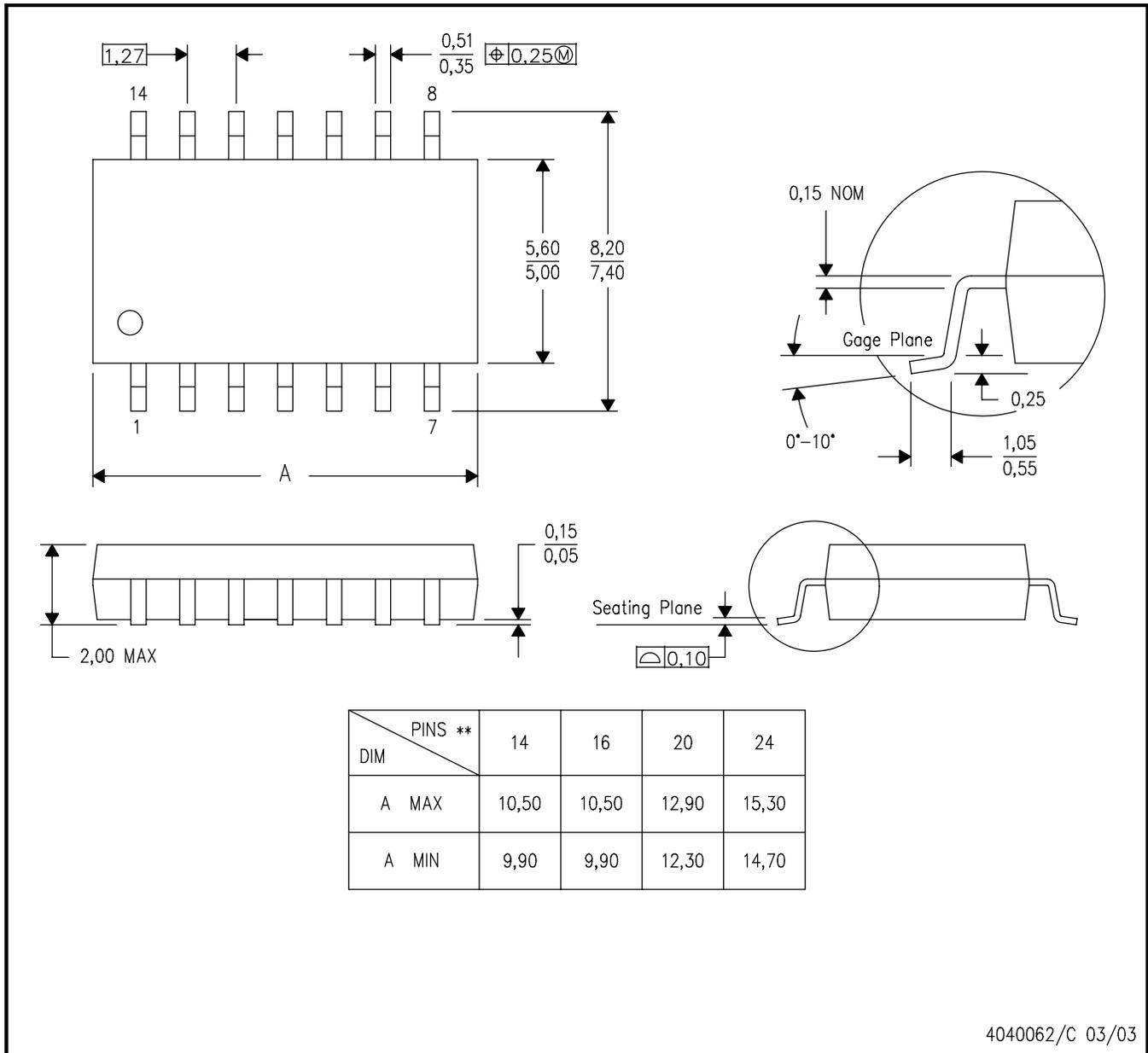
- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

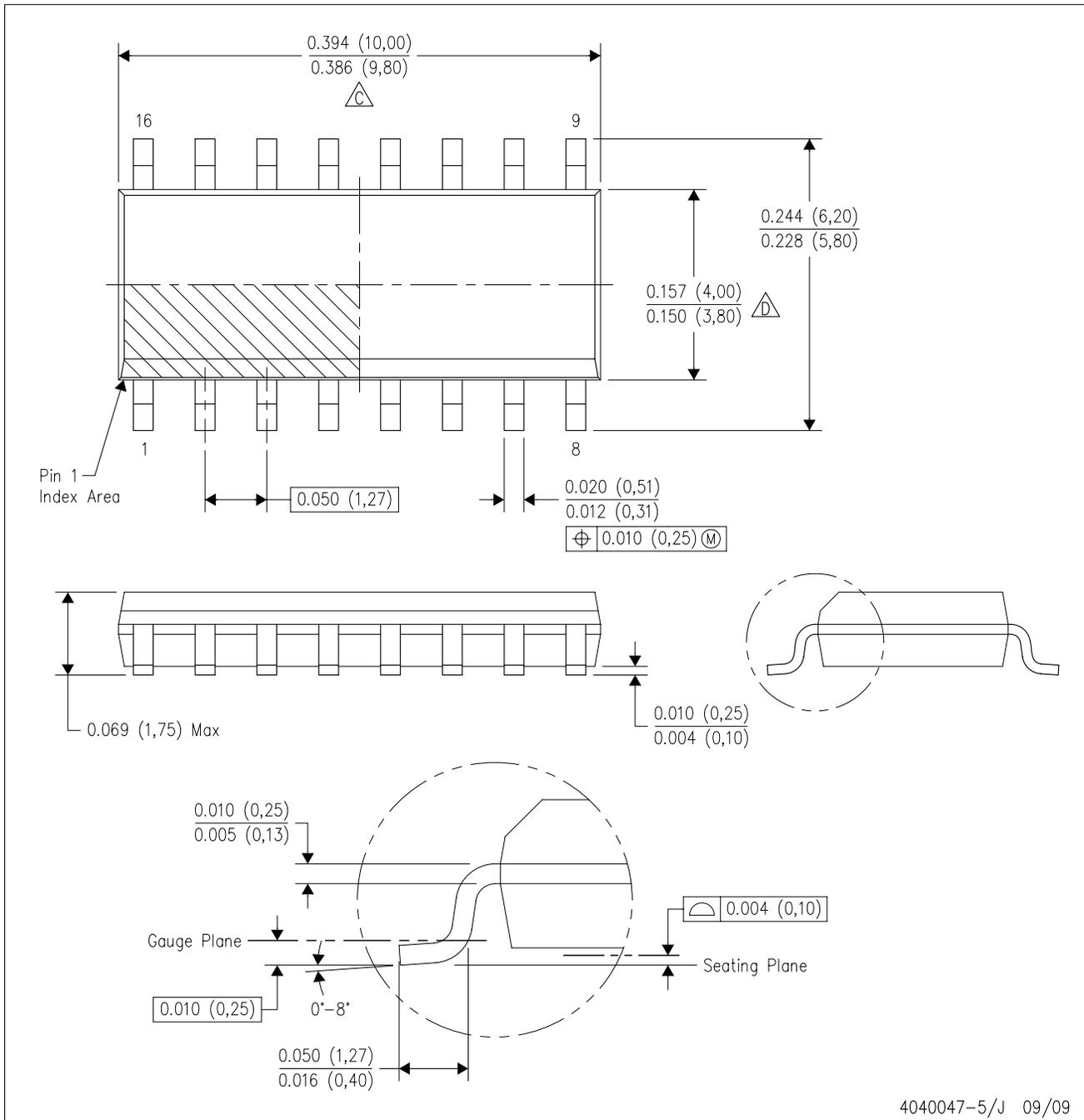
14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

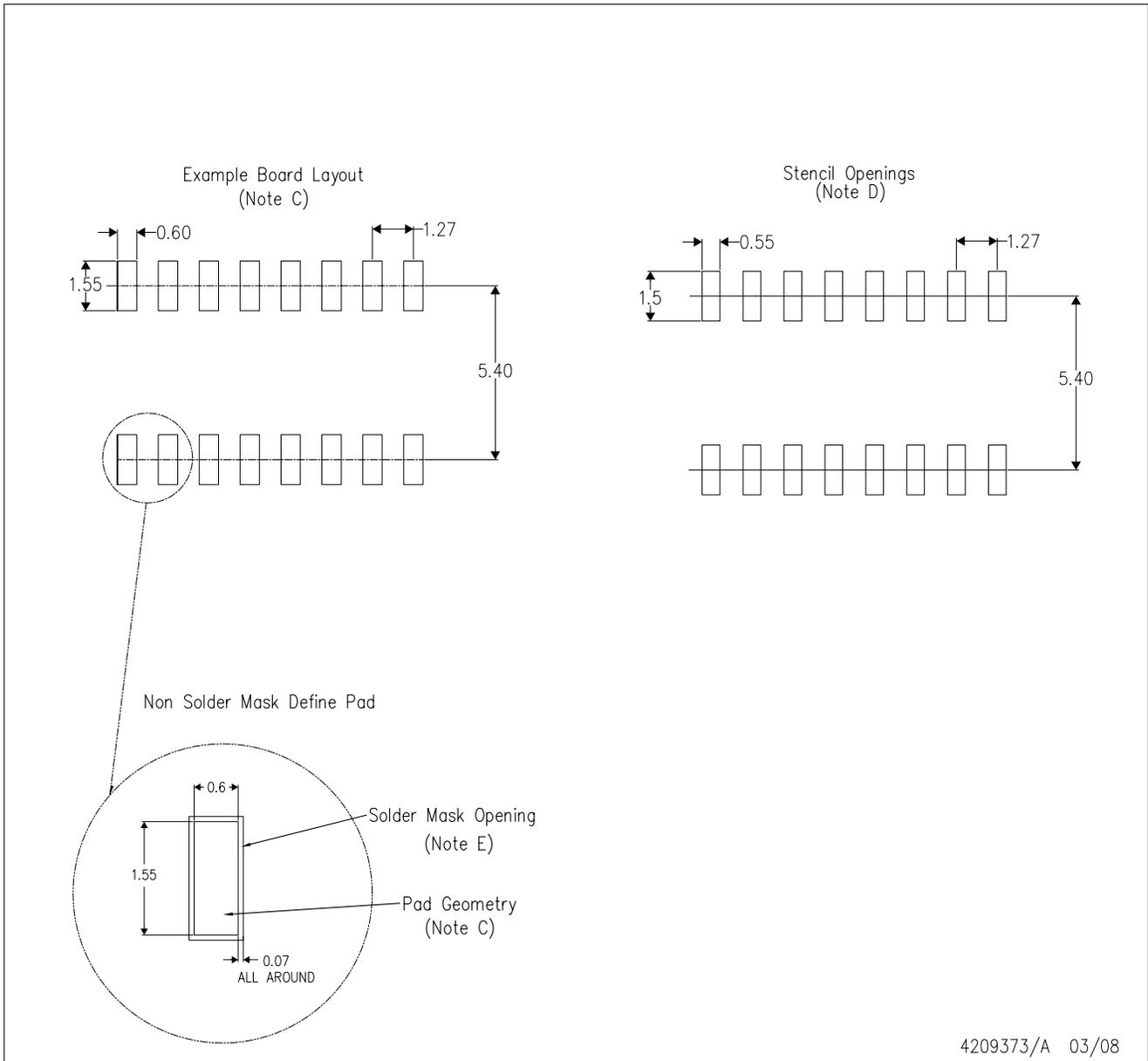
D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 -  D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AC.

D(R-PDSO-G16)



4209373/A 03/08

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

